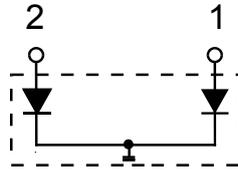
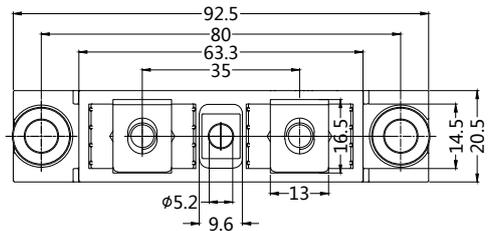
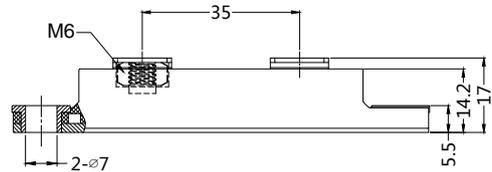


# SRUD300CT

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules



Dimensions in mm (1mm=0.0394")



	V <sub>RSM</sub> V	V <sub>RRM</sub> V
SRUD30040CT	400	400
SRUD30060CT	600	600

Symbol	Test Conditions	Maximum Ratings	Unit
I <sub>FRMS</sub>	T <sub>C</sub> =85°C	235	A
I <sub>FAVM</sub>	T <sub>C</sub> =85°C; rectangular, d=0.5, per chip	150	
I <sub>FRM</sub>	t <sub>p</sub> <10us; rep. rating, pulse width limited by T <sub>VJM</sub>	TBD	
I <sub>FSM</sub>	T <sub>VJ</sub> =45°C	t=10ms (50Hz), sine t=8.3ms (60Hz), sine	A
	T <sub>VJ</sub> =150°C	t=10ms(50Hz), sine t=8.3ms(60Hz), sine	
I <sup>2</sup> t	T <sub>VJ</sub> =45°C	t=10ms (50Hz), sine t=8.3ms (60Hz), sine	A <sup>2</sup> s
	T <sub>VJ</sub> =150°C	t=10ms(50Hz), sine t=8.3ms(60Hz), sine	
T <sub>VJ</sub>		-40...+175	°C
T <sub>stg</sub>		-40...+125	
T <sub>Hmax</sub>		110	
P <sub>tot</sub>	T <sub>case</sub> =25°C	480	W
M <sub>d</sub>	Mounting torque (M5)	2.50-4/22-35	Nm/lb.in.
	Terminal connection torque (M5)	2.50-4/22-35	
ds	Creeping distance on surface	12.7	mm
da	Strike distance through air	9.6	mm
a	Maximum allowable acceleration	50	m/s <sup>2</sup>
Weight		160	g

**Sirectifier®**

# SRUD300CT

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

Symbol	Test Conditions	Characteristic Values		Unit
		typ.	max.	
<b>I<sub>R</sub></b>	$T_{VJ}=25^{\circ}\text{C}; V_R=V_{RRM}$		0.05	mA
	$T_{VJ}=25^{\circ}\text{C}; V_R=0.8 \cdot V_{RRM}$		0.05	
	$T_{VJ}=125^{\circ}\text{C}; V_R=0.8 \cdot V_{RRM}$		5	
<b>V<sub>F</sub></b>	$I_F=150\text{A}; T_{VJ}=125^{\circ}\text{C}$		1.25	V
	$T_{VJ}=25^{\circ}\text{C}$		1.55	
	$I_F=300\text{A}; T_{VJ}=125^{\circ}\text{C}$		1.95	
	$T_{VJ}=25^{\circ}\text{C}$		2.09	
<b>V<sub>TO</sub></b>	For power-loss calculations only		1.01	V
<b>r<sub>T</sub></b>	$T_{VJ}=125^{\circ}\text{C}$		2.85	m $\Omega$
<b>R<sub>thJH</sub></b> <b>R<sub>thJC</sub></b>	DC current		0.550	K/W
	DC current		0.450	
<b>t<sub>rr</sub></b> <b>I<sub>RM</sub></b>	$I_F=1.0\text{A}; T_{VJ}=100^{\circ}\text{C}$ $V_R=300\text{V}; T_{VJ}=25^{\circ}\text{C}$ $-di/dt=200\text{A}/\mu\text{s}; T_{VJ}=100^{\circ}\text{C}$	50	60 14 21	ns A A

### FEATURES

- \* International standard package
- \* Copper base plate
- \* Glass passivated chips
- \* Short recovery time
- \* Low switching losses
- \* RoHS compliant

### APPLICATIONS

- \* Antiparallel diode for high frequency switching devices
- \* Free wheeling diode in converters and motor control circuits
- \* Inductive heating and melting
- \* Uninterruptible power supplies (UPS)
- \* Ultrasonic cleaners and welders

### ADVANTAGES

- \* High reliability circuit operation
- \* Low voltage peaks for reduced protection circuits
- \* Low noise switching
- \* Low losses



# SRUD300CT

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

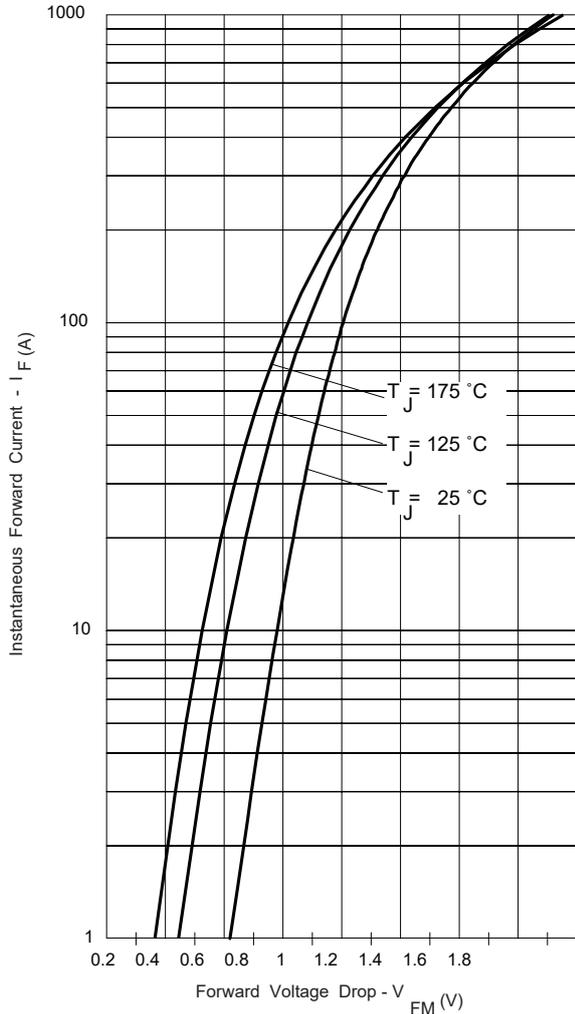


Fig. 1 - Typical Forward Voltage Drop Characteristics

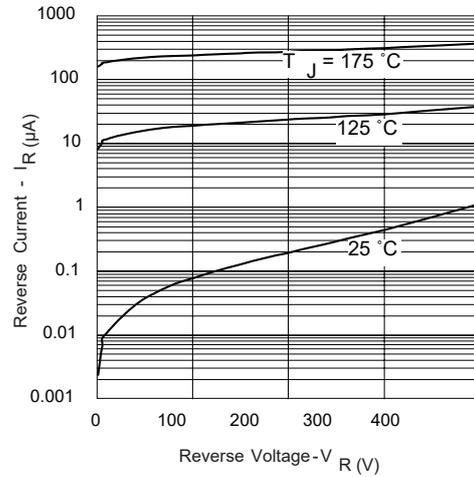


Fig. 2 - Typical Values Of Reverse Current Vs. Reverse Voltage

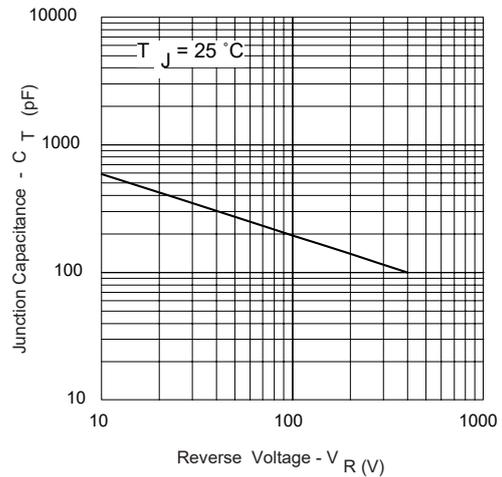


Fig. 3 - Typical Junction Capacitance Vs. Reverse Voltage

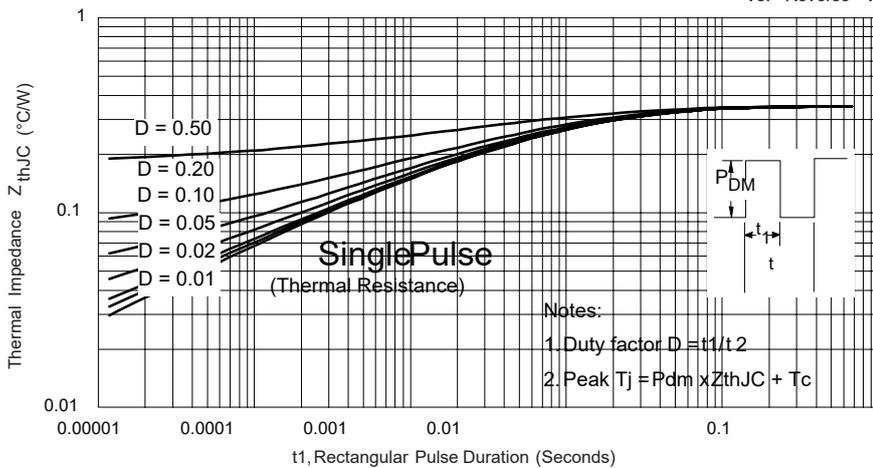


Fig. 4 - Max. Thermal Impedance  $Z_{thjC}$  Characteristics



# SRUD300CT

## Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

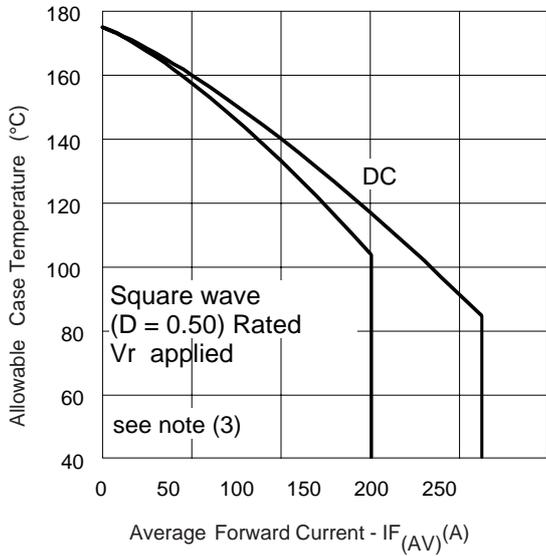


Fig. 5 - Max. Allowable Case Temperature Vs. Average Forward Current

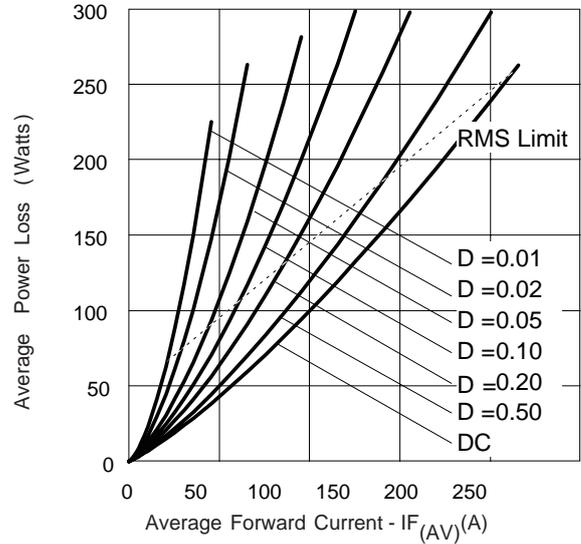


Fig. 6 - Forward Power Loss Characteristics

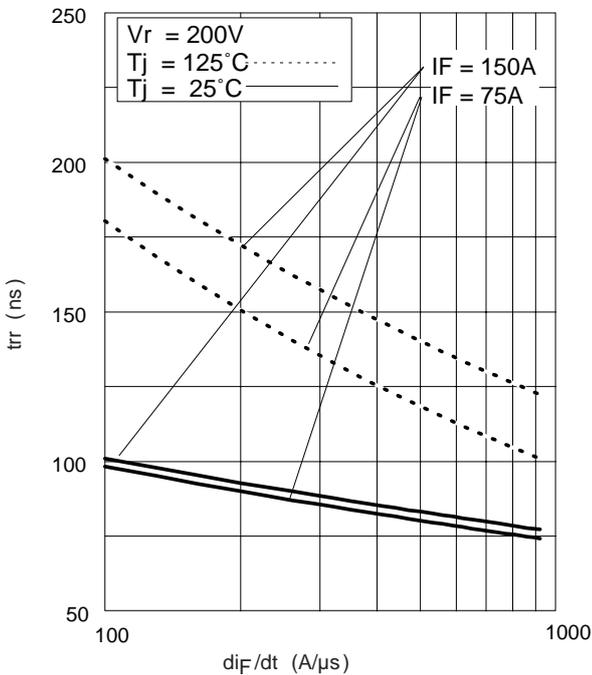


Fig. 7 - Typical Reverse Recovery time vs.  $diF/dt$

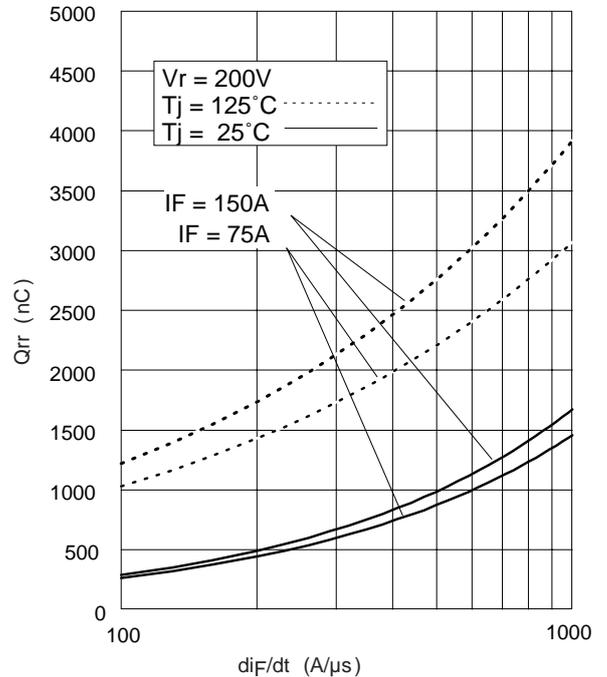


Fig. 8 - Typical Stored Charge vs.  $diF/dt$